



PK1070(v1.0) March 24, 2020

100% Material Declaration Data Sheet for XQZU9EG-FFRC900

Average Weight : 12.8785 g

Component	Substance Description	CAS # or Description	% of component	Use in product	Component weight / substance weight (in grams)	Component % of total
Silicon die					0.416388	3.233%
	Silicon	7440-21-3	100.00	basis	0.416388	
Bump					0.017917	0.139%
	Tin	7440-31-5	98.20	basis	0.017594	
	Silver	7440-22-4	1.80	basis	0.000323	
Underfill					0.056900	0.442%
	Bisphenol F type liquid	9003-36-5	15.00	basis	0.008535	
	1,6-Bis(2,3-	27610-48-6	10.00	basis	0.005690	
	Bisphenol A type liquid	25068-38-6	5.00	basis	0.002845	
	Amine type hardener	trade secret	10.00	basis	0.005690	
	Silicon dioxide	60676-86-0	58.00	filler	0.033002	
	Carbon black	1333-86-4	1.00	color agent	0.000569	
	Additives	trade secret	1.00	additives	0.000569	
Solder paste					0.008192	0.064%
	Tin	7440-31-5	54.50	metal	0.004465	
	Lead	7439-92-1	33.00	metal	0.002703	
	Additives	trade secret	12.50	flux	0.001024	
Capacitor 1					0.220160	1.710%
	Barium	12047-27-7	80.69	Ceramic	0.177652	
	Manganese	1313-13-9	1.31	Ceramic	0.002879	
	Nickel	7440-02-0	9.08	Internal Electrode	0.019984	
	Copper	7440-50-8	0.68	Termination	0.001490	
	Glass oxide	65997-17-3	0.02	Termination	0.000034	
	Nickel	7440-02-0	3.13	Plating	0.006893	
	Tin	7440-31-5	4.69	Plating	0.010331	
	Lead	7439-92-1	0.41	Plating	0.000898	
Heat sink					7.589200	58.929%
	Copper	7440-50-8	98.35	Main material	7.463978	
	Nickel	7440-02-0	1.65	Main material	0.125222	
Heat sink TIM					0.119000	0.924%
	Treated aluminum oxide	trade secret	80.00	Main material	0.095200	
	Dimethyl siloxane, dimethylvinyl-terminated	68083-19-2	20.00	Main material	0.023800	
Solder ball					0.856617	6.652%
	Tin	7440-31-5	63.00	Main material	0.539669	
	Lead	7439-92-1	37.00	Main material	0.316948	
Substrate					3.594121	27.908%
	Copper	7440-50-8	39.43		1.417045	
	Tin	7440-31-5	0.20		0.007305	
	Lead	7439-92-1	0.12		0.004291	
	Core	N/A	42.78		1.537600	
	ABF	N/A	16.04		0.576600	
	Solder Mask	N/A	1.43		0.051280	

Revision History

Date	Version	Description of Revisions
9/10/2019	1.0	Initial Xilinx Release.

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